

Specification

Machine name - **Dry Process Dicing**

The DTX-MDB provides processes for GaAs, RFICs, optical devices MEMS devices with delicate topside structures.



Features

- 1] High throughput for GaAs RFICs.
- 2] Dry process ideal for MEMS processing
- 3] Optional cassette loading for high volume production. Cleaving of mirror facets for edge emitting laser diodes.
- 4] Positioning system feedback mechanism is optical encoder
- 5] Diamond type V-4-64, scribe angle – 28 to 40 degrees, scribe force is programmable.
- 6] Relative break position 0 to 5mm. provide realignment feature during breaking
- 7] GUI based with Microsoft XP. Pattern recognition vision system.
- 8] Up to 8 inch sample size support
- 9] Programmed vision pattern recognition.